



**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Continuation-in-Part Application of  
Seigi AOYAMA et al.  
Application S/N 09/892,630  
Filed: June 28, 2001  
For: LEAD-FREE SOLDER, AND CONNECTION LEAD AND ELECTRICAL  
COMPONENT USING SAID LEAD-FREE SOLDER

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: Art Unit: 2827  
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: Examiner: T. Dinh  
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**REQUEST FOR RECONSIDERATION**

Honorable Assistant Commissioner  
for Patents  
Washington, DC 20231

Sir:

This Request for Reconsideration is filed concurrently with the filing of a Request for Continued Examination and further to the Amendment filed on March 19, 2003, and the Advisory Action issued on May 6, 2003.